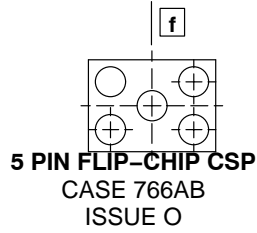
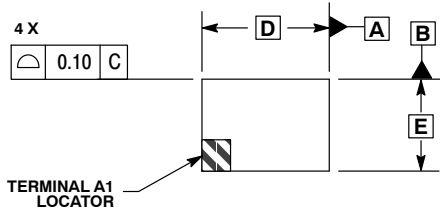


X M ■

X = Specific Device Code
M = Date Code
■ = Pb Free Package
(Note: Microdot may be in either location)



DATE 04 JUN 2003



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.680	
A1		
A2	0.380	0.430
D	1.330 BSC	
E		
b	0.290	0.340
e	0.500 BSC	

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DESCRIPTION:	5 PIN FLIP-CHIP CSP	PAGE

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⊕	∅ 0.05	C	A	B
	∩ 0.03	C		